

Title (en)
TITANIUM COPPER FOR ELECTRONIC COMPONENTS

Title (de)
TITANKUPFER FÜR ELEKTRONISCHE KOMPONENTEN

Title (fr)
TITANE-CUIVRE POUR COMPOSANTS ÉLECTRONIQUES

Publication
EP 3460082 B1 20200513 (EN)

Application
EP 18196026 A 20180921

Priority
JP 2017182751 A 20170922

Abstract (en)
[origin: EP3460082A2] The present invention is intended to improve bending workability of titanium copper for electronic components, and to provide a titanium copper for electronic components, which has excellent bending workability even when subjected to beating process, and to provide a method for manufacturing the same. One embodiment of the present invention is a titanium copper, comprising 2.0 to 4.5 mass% of Ti, and at least one element selected from the group consisting of Fe, Co, Ni, Cr, Zn, Zr, P, B, Mo, V, Nb, Mn, Mg, and Si in total of 0 to 0.5 mass% as a third element(s), and the rest consisting of copper and inevitable impurities, wherein a work-hardening exponent is 0.05 to 0.25, and an X-ray diffraction integrated intensity $I_{\{200\}}$ from the $\{200\}$ crystal face on the surface of the titanium copper and an X-ray diffraction integrated intensity I_0 of a pure copper standard powder satisfy the following relation: $0.15 \leq I_{\{200\}} / I_0 \leq 0.70$.

IPC 8 full level
C22C 9/00 (2006.01); **C22F 1/08** (2006.01)

CPC (source: EP RU)
C22C 9/00 (2013.01 - EP RU); **C22F 1/08** (2013.01 - EP RU); **H01B 1/02** (2013.01 - RU); **H01B 1/026** (2013.01 - EP); **C22F 1/02** (2013.01 - EP)

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)
EP 3460082 A2 20190327; **EP 3460082 A3 20190515**; **EP 3460082 B1 20200513**; JP 2019056167 A 20190411; JP 6310131 B1 20180411; RU 2690737 C1 20190605

DOCDB simple family (application)
EP 18196026 A 20180921; JP 2017182751 A 20170922; RU 2018133256 A 20180920